



Ultra-Thin and Micro Heat Pipe Manufacturing and Their Applications

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Message from the Guest Editor

The reducing size and improving performance of electronic devices such as smartphones, tablet computers and micro/meso-spacecrafts have led to a dramatic increase of heat fluxes generated by the internal electronic components. Thermal management has been becoming a bottleneck that restricts the further development of electronic devices. Ultra-thin and micro heat pipes, as two-phase passive heat spreaders, are an effective and promising solution for the cooling of mobile electronics.

This Special Issue is focused on the manufacturing process and the application status of ultra-thin and micro heat pipes. Articles focusing on new fabrication technologies, including but not limited to different materials, novel wick designs and assembly techniques, new test methods, and application extension of the ultra-thin and micro heat pipe, will be welcomed and reviewed as soon as possible.





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Message from the Editorial Board

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